

Name : Jagatbondhu Mondal

ID : 2121210051

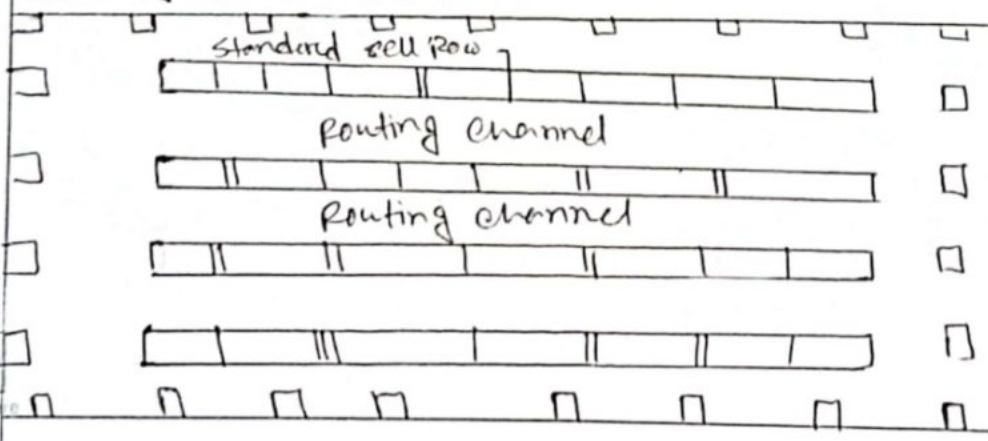
CSI : 427 (VLSI design and Analysis)

### Ans to the Qus no. 1(a)

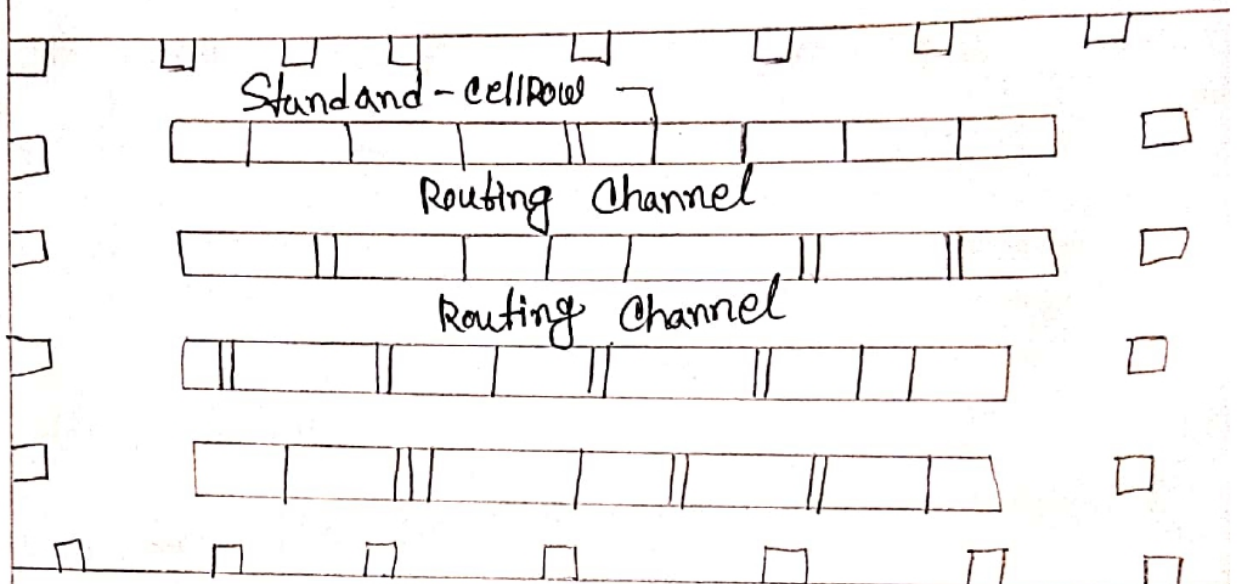
#### Standard cell based design:

A standard cell based design requires development of a full custom mask set. The standard cell is also known as the polycell. In this approach all of the commonly used logic cells are developed characterized and stored in a standard cell library.

A library may contain a few hundred cells including inverters, NAND, NOR, complex AOI, OAI, gates, D-latches and flip-flops. Each gate type can be implemented in several versions to provide a depth of driving capability for different loads. For example, an inverter gate can have standard, double and quadruple size. So that the chip designer can select the proper size to obtain high circuit speed and layout density each according to several different categories such as.



density Each All the according to Several different categories such as.



Figures:- Floor Plan Standard Cell based design

- (i) Delay time versus load capacitance.
- (ii) circuit simulation model.
- (iii) Timing simulation model.
- (iv) fault simulation model.
- (v) Cell data for Places - and route.
- (vi) mas R data.
- (vii) Automated placement of the cell.  
and routing.

P.-04

A voltage called electromotive force is quantitative expression of the potential difference change between two points



$$Q_s = \text{Surface}$$

Consider the cross sectional view of channel

$$V_s = V_B = 0 \text{ to } E_{pm} = q_{ms} - E_{FP}$$

$$V_c = (y=0) = V_s \text{ (and } V_c (y=2))$$

the spatial geometry equation made

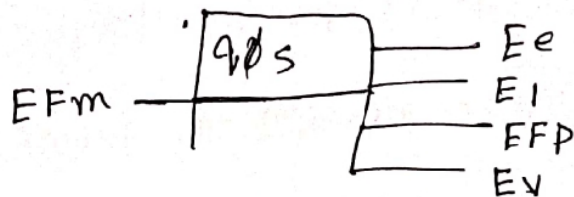
indicate

$$dn = \frac{dy}{Q_{msy}} \times 10^{-7} \text{ cm}$$



P.-04

A voltage called electromotive force is quantitative expression of the potential difference change between two points



$$\phi_s = \text{Surface}$$

Consider the cross sectional view of channel

$$V_s = V_B = 0 \text{ to } E_{pm} = Q_{ms} - E_{FP}$$

$$V_c = (y=0) = V_s \text{ (and } V_c (y=2)$$

the spatial geometry equation made

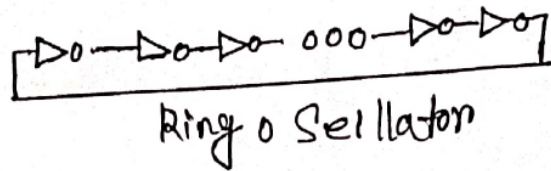
in dicat

$$dn = \frac{dy}{Q_{msy}} \times 10^{-7} \text{ cm}$$



~~2-0A~~  
2-0A

## Oscillation Solutions:-



The logical effort of the inverter is  $g=1$  by definition. The electrical effort of each inverter is also 1 because it drives single identical load, the parasitic delay is also 1.

The delay of each stage is

$$\begin{aligned}d &= gb + p \\ &= 1 \times 1 + 1 \\ &= 2\end{aligned}$$

An  $N$ -stage ring oscillator has a period of  $2N$  stage delays because a value must propagate twice around the ring to regain the original polarity.

P.T.O

Therefore the period is  $T = 2 \times 2N$  The frequency  
is the of the period  $1/4n$

A 31-stage ring oscillator in a 65nm process

has a frequency  $1/(4 \times 31 \times 3) = 2.7 \text{ GHz}$

Note that ring oscillators are often used

as process monitors to judge if a particular

chip is faster or slower than nominally ex-

pected one the inventors should be

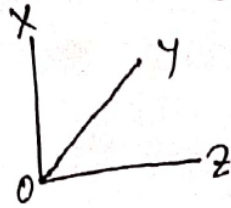
replead with the nomim replead with

NAND gate to turn the ring.



2B

Ans: Linear delay model in vlsi :-



This post talks about logical effort and parasitic delay in linear delay model in vlsi. as we show before delay linearly depend on the sum of the gate. normalized delay expressed as the sum of parasitic delay  $p$  and effort delay  $f_d = p + f$  the effort delay depends on the fan-out not the gate  $f = gh$  here  $g$  is a logical effort what is fan-out or electrical effort was driving another identical copy.



p-08

⊕ In general the propagation delay of a

gate can be written  $= t_{intrinsic} + t_{effort}$

$t_{intrinsic}$  is the delay due to intrinsic capacitance

$t_{effort}$  is the effort delay or stage effort

and depends on the complexity and fanout of the gate.

⊕ The stage effort is  $f = gh$  with the complexity represented by the logical effort.

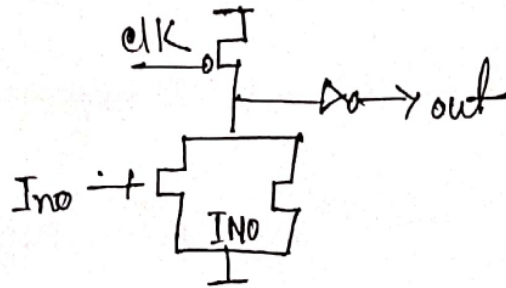
⊕ An inverter is defined to have logical effort of 1.

⊕ A gate driving  $n$  identical - copies of itself is said to have an electrical effort  $n$ .

⊕ The electrical effort of non-identical copies of the gate on any type load to be  $n = C_{out} / C_{in}$ .

3.A

Domino nose doudgets:- The rapid advantage  
in VLSI content in Domina with block  
Diagram



Domina Gate.

During the precharge phase when the clock is low the pre charging gets on and the dynamic node is connected to the VDD and gets precharge to VDD when clock goes high the evaluation phase starts and the output gets evaluated with the pull down network and conditionally the above proposed circuit has reduce no.



The Domino Logic Stage Consists of Logic realized using N-mos pull down network pull up the work consists of a single pre charge dynamic node to logic high as shown. The dynamic node is cascaded into static noise invertor and can be corrected. The compensation called keeper is used. In the first Domino proposal the gate of the keeper is connected to the ground.



4.A Source of Power Dissipation: The power dissipation in CMOS circuits comes from two components.

① Dynamic dissipation.

② Static dissipation.

Dynamics ① due to charging and discharging load capacitance as gates switch.

② Short circuit while the transition of leakage current when the system is not powered on is in stand by mode. In circuits there are several sources of leakage current including subthreshold leakage, direct leakage, drain induced barrier lowering and n-well tunnel current, gate leakage etc. Power in active effort the dynamic power.

Static Power:- when a CMOS circuit is in an idle state there is still some static power dissipation. In a silicon chip there are millions of transistors and the current is comparable to leakage and sub-threshold currents depend upon processing parameters.

$$I_{leak} = A \cdot J_s (e^{-kT})$$

A is the junction area.

$J_s$  is the current density of electrons

k is Boltzmann's constant.

Diode formation due to MOS structure is inherent in. increase in temperature millions of transistors to the static power dissipation.